



Features

- 4-Pin Dip
- Fast warm-up
- TCXO replacement for better short term stability
- Frequency Range, 10 MHz to 40 MHz
- Standard frequencies, 10,19.44,20,24.576,25,26,38.88, 40 MHz);

Applications

- Base stations
- Test equipment
- Synthesizers
- Military communication equipment

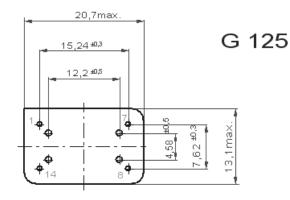
Performance Specifications

	Frequency Stabilities¹ (10 to 40 MHz)					
Parameter	Min	Typical	Max	Units	Condition	
vs. operating temperature range (referenced to +25°C)	-5 -10 -10		+5 -10 -10	ppb ppb ppb	-40 to +85°C -40 to +85°C -40 to +95°C	
Initial tolerance vs. supply voltage change vs. load change vs. aging / day vs. aging / year vs. aging / 10 years	-0.2 -10 -10 -1.0 -100		+0.2 +10 +10 +1.0 +100 +1000	ppm ppb ppb ppb ppb ppb	at time of shipment, nominal EFC V _s ±5% static Load ±5% static after 30 days of operation after 30 days of operation after 30 days of operation	
hold over						
start up time						
Warm-up time			3	minutes	to ±100ppb of final frequency (1 hour reading) @ +25°C	

Performance Specifications

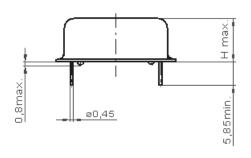
Supply Voltage (Vs)						
Parameter	Min	Typical	Max	Units	Condition	
Supply voltage (standard)	3.135	3.3	3.465	VDC		
	4.75	5.0	5.25	VDC		
Danis			2.5	Watts	during warm-up	
Power consumption			1.0	Watts	steady state @ +25°C	
			RF Outpu	t		
Signal [standard]		HCI	MOS			
Load		15		pF		
Signal Level (Vol)			0.4	VDC	with Vs=3.3V and 15pF Lo	ad
Signal Level (Vol)			0.5		with Vs=5.0V and 15pF Lo	ad
Signal Level (Voh)	2.4			VDC	with Vs=3.3V and 15pF Lo	ad
Signal Level (Voh)	3.5				with Vs=5.0V and 15pF Lo	ad
rise time			5	ns		
fall time			5	ns		
Duty Cycle	45		55	%	@ (Voh-Vol)/2	
		Frequ	uency Tunir	ıg (EFC)		
Tuning Range		Fixed OCX	O; No adjust			Opti- on ⁵
	±1.0		±3	ppm		QO IO
Linearity		10	0%			
Tuning Slope	Positive					
Control Voltage Range	0.0	1.4	2.8	VDC	with Vs=3.3V	
	0.0	2	4.0	VDC	with Vs=5.0V	
Additional Parameters						
Phase Noise ³		-85 -121 -140 -152 -155		dBc/Hz dBc/Hz dBc/Hz dBc/Hz dBc/Hz	1 Hz 10 Hz 100 Hz 1 kHz 10 kHz	@ 20MHz
Weight			8.0	g		
Processing & Packing	ŀ	Handling & Pr				
		Absolu	te Maximur	n Ratings		
supply voltage (Vs)			5.5	V	with Vs=3.3 & 5.0 VDC	
Output Load			50	pF		
Operable Temperature Range	-45		+85	°C		
Storage Temperature Range	-45		+85	°C		

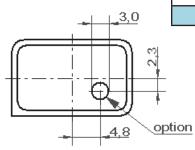
Outline Drawing / Enclosure

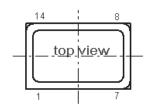


OX-400		
Height "H"	Pin Length "L"	
8.5	5.85min.	

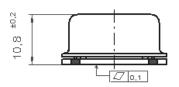
Pin Connections			
1	Electronic Frequency Control Input (EFC)		
7	Ground (Case)		
8	RF Output		
14	Supply Voltage Input		

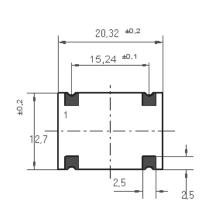


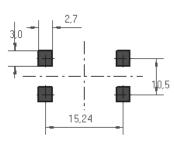




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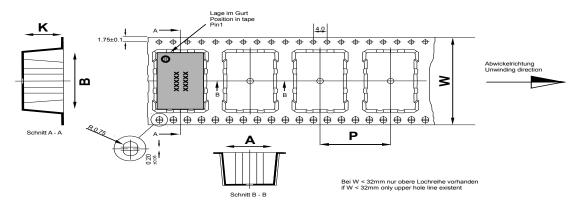
Padvorschlag PCB Layout

OX-401			
Height "H"	Pin Length "L"		
10.8	N/A		

Pin Connections		
1	Electronic Frequency Control Input (EFC)	
7	Ground (Case)	
8	RF Output	
14	Supply Voltage Input	

Dimensions in inches mm

Standard Shipping Method (OX-401)



Maßangaben in mm:

A, B und K Maße von Bauelement abhängig

Fertigungstoleranzen entsprechen der DIN IEC 286-3

Dimension in mm:

A, B und K are dependent uppon component dimensions production tolerance complying DIN IEC 286-3

All dimensions in millimeters unless otherwise stated

Enclosure Type	Tape Width W (mm)	Quantity per meter	Quantity per reel	Dimension P
Typ OX-401	32	50	250	20

Standard Shipping Method (OX-400)

Enclosure Type	Method	colloums	rows	Quantity per Tray
Typ OX-400	Tray	10	8	80

Recommended Reflow Profile

IPC/JEDEC J-STD-020 (latest revision)

Additional Information:

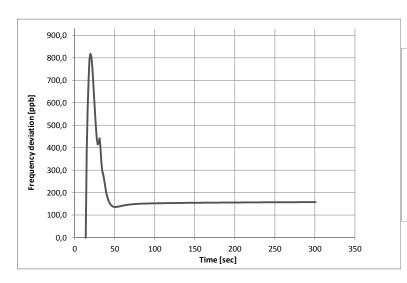
This SMD oscillator has been designed for pick and place reflow soldering.

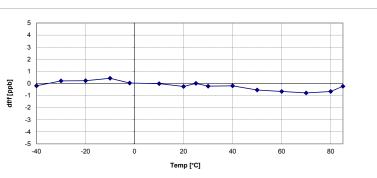
SMD oscillators must be on the top side of the PCB during the reflow process.

Additional Environmental Conditions

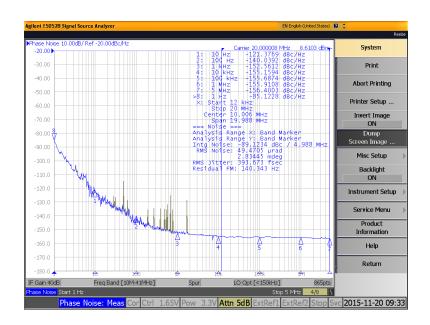
Parameter	Description
Rapid temperature changes	MIL-883-1010 Cond B 1000 cycles -55/125C
Vibration	MIL-STD-883 Meth 2007 Cond A 20G 20-2000Hz 4x in each 3axis 4 min
Shock	JESD22-B104-B 100G 1,5ms 6 shocks in each direction
Solderability	J_STD_002C Cond A, Through hole device/ Cond. B, SMD 255C (diving time 50,5sec.) Dip+Look with 8h damp pre-treatment: solder wetting >95%
Solvent resistance	MIL-STD-883 Meth 2015 Solv. 1,3,4
ESD	HBM JESD22-A114-E Class 2 10* 2000V
Moisture Sensit.	Level 1 JESD22-A113-B
RoHS compliance	100% RoHS 6 compliant
Washable	washable device

typical perforamce data		
typical warm up	typical temp stability	
@ OX-400-EAE-1080-20M000	@ OX-400-EAE-1080-20M000	

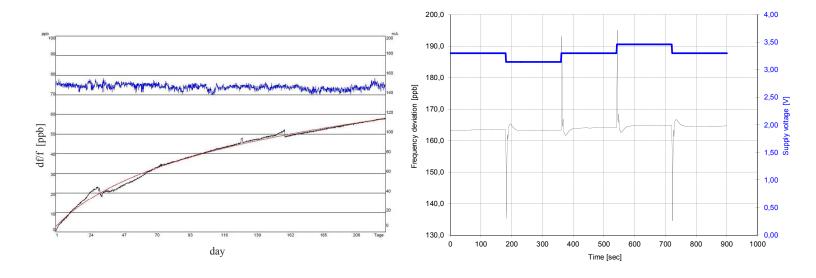




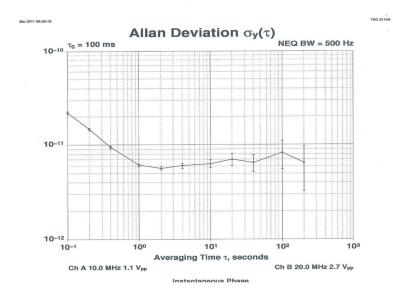
typical Phase Noise	
@ OX-400-EAE-1080-20M000	@ OX-400-EAE-1080-20M000

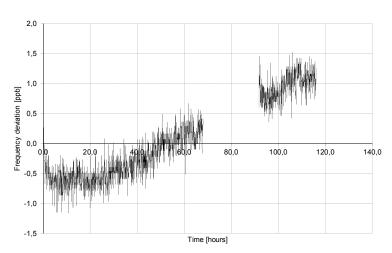


typical perforamce data typical aging data typical frequeny vs. supply voltage @ OX-400-EAE-1080-20M000 @ OX-400-EAE-1080-20M000



typical ADEV	typical retrace
@ OX-400-EAE-1080-20M000	@ OX-400-EAE-1080-20M000





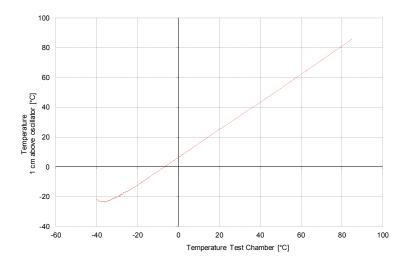
typical perforamce data

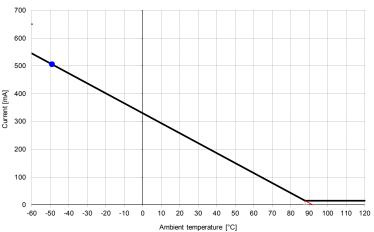
typical case temperature vs outside temperature

typical power consumption vs operating temperauture

@ OX-400-EAE-1080-20M000

@ OX-400-EAE-1080-20M000



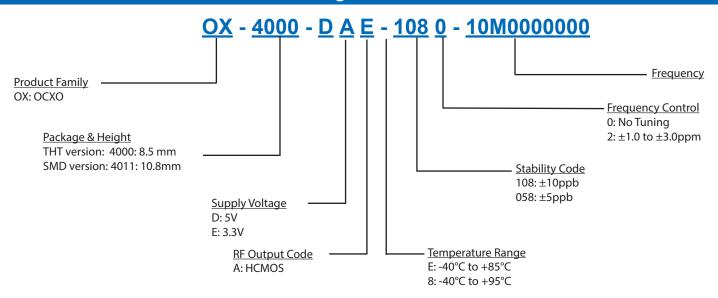


recomended power on time after x days of power off

@ OX-400-EAE-1080-20M000



Ordering Information



Notes:

- 1. Contact factory for improved stabilities or additional product options. Not all options and codes are available at all frequencies.
- 2. Unless other stated all values are valid after warm-up time and refer to typical conditions for supply voltage, frequency control voltage, load, temperature (25°C).
- 3. Phase noise degrades with increasing output frequency.
- 4. Subject to technical modification.
- 5. Contact factory for availability.



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